SDLS079

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent 4-input NAND gates.

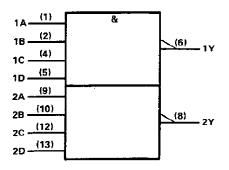
The SN5420, SN54LS20, and SN54S20 are characterized for operation over the full military range of -55 °C to 125 °C. The SN7420, SN74LS20, and SN74S20 are characterized for opertion from 0 °C to 70 °C.

FUNCTION TABLE	(each	gate)
----------------	-------	-------

	INP	UTS	OUTPUT	
A	8	с	D	Y
н	н	Н	н	Ļ
L	х	х	X	н
х	L	х	x	н
х	х	L	×	н
х	х	х	L	н

logic symbol[†]

Ľ



 $^{\dagger} \text{This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.$

Pin numbers shown are for D, J, N, and W packages.

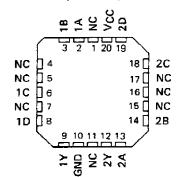
SN5420, SN54LS20, SN54S20, SN7420, SN74LS20, SN74S20 DUAL 4-INPUT POSITIVE-NAND GATES

DECEMBER 1983-REVISED MARCH 1988

SN5420J PACKAGE SN54LS20, SN54S20J OR W PACKAGE SN7420N PACKAGE SN74LS20, SN74S20D OR N PACKAGE (TOP VIEW)
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
SN5420 W PACKAGE (TOP VIEW)

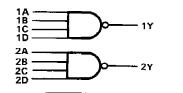
1A	٦	U14	1 D
1Y		13	1C
NC	Д3	12]	1B
Vcc	□4	пþ	GND
NC	₫5	10	2Y
2A	Дб	de 🛛	2D
2B	<u>d</u> ⁷	8	2C

SN54LS20, SN54S20 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram



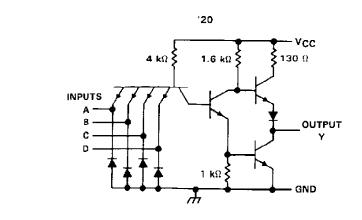
positive logic Y = $\overline{A \cdot B \cdot C \cdot D}$ or Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}

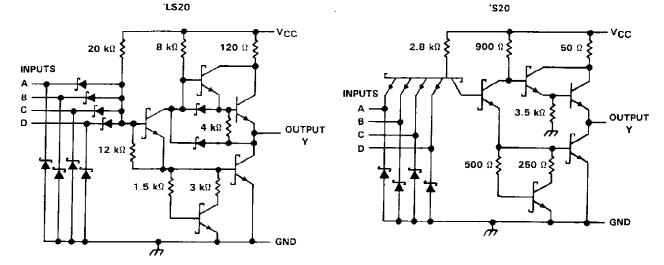
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Taxas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS INSTRUMENTS

SN5420, SN54LS20, SN54S20, SN7420, SN74LS20, SN74S20 DUAL 4-INPUT POSITIVE-NAND GATES

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	· · · · · · · · · · · · · · · · · · ·
	5.5 V
'LS20	
Operating free-air temperature range:	SN54'55°C to 125°C
	SN74' 0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminals.



recommended operating conditions

	· · · · · · · · · · · · · · · · · · ·		SN5420 SN7420					
		MIN	NOM	MAX	MIN	NOM	МАХ	GINT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	v
Vін	High-level input voltage	2			2			v
VIL	Low-level input voltage			0.8			0.8	v
юн	High-level output current			0.4			- 0.4	mΑ
IOL	Low-level output current			16			16	ΜA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS T		SN5420			\$N7420			
PARAMETER		TEST CONDITIONS I	MIN	TYP‡	MAX	MIN	түр‡	MAX	UNIT	
VIK	V _{CC} = MIN,	lı = — 12 mA		-	- 1.5			1.5	V	
⊻он	V _{CC} = MIN,	V _{IL} = 0.8 V, I _{OH} = − 0.4 mA	2.4	3.4		2.4	3.4		V	
Vol	Vcc = MIN,	V _{IH} =2V, l _{OL} = 16 mA		0.2	0.4		0.2	0.4	V	
կ	V _{CC} = MAX,	V ₁ - 5.5 V			1		-	1	mA	
ін	V _{CC} = MAX,	V ₁ = 2.4 V			40			40	μA	
ίιL	VCC = MAX,	V ₁ = 0.4 V			- 1.6			- 1.6	mΑ	
los§	V _{CC} = MAX		- 20		- 55	- 18		- 55	mA	
ICCH	V _{CC} = MAX,	VI = DV		2	4		2	4	mΑ	
ICCL	V _{CC} = MAX,	V ₁ = 4.5 V		6	11		6	11	mA	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. § Not more than one output should be shorted at a time.

1

switching characteristics, V_{CC} = 5 V, T_A = 25° C (see note 2)

PARAMETER	FROM (INPUT)	то (оитрит)	TEST CONDITIONS	MIN	TYP	мах	UNIT
^t ₽LH	A =	Y			12	22	ns
TPHL	Any	Ť	R _L =400 Ω, C _L =15 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS20, SN74LS20 DUAL 4-INPUT POSITIVE-NAND GATES

recommended operating conditions

	S	SN54LS20			SN74LS20			
	MIN	NOM	МАХ	MIN	NOM	MAX	UNIT	
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH High-level input voltage	2			2			v	
VIL Low-level input voltage			0.7			0.8	v	
IOH High-level output current			- 0.4			- 0.4	mA	
IOL Low-level output current			4			8	mA	
T _A Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T			SN54LS20			SN74LS20			
FANAMEIEN		TEST CONDIT	10031	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
Vik	VCC = MIN,	i _l = – 18 mA				- 1.5			— 1 .5	V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3,4		2.7	3.4		v
Max	V _{CC} = MIN,	V _{IH} = 2 V,	loL = 4 mA		0.25	0.4			0.4	v
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	10L = 8 mA					0.25	0.5	
4	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
ЧН	VCC = MAX,	V ₁ = 2.7 V				20			20	μA
۱۱L	V _{CC} = MAX,	VI = 0.4 V				- 0.4			- 0.4	mΑ
IOS §	VCC = MAX			- 20		- 100	- 20		- 100	mΑ
Іссн	V _{CC} = MAX,	V = 0 V			0.4	0.8	-	0.4	0.8	mA
CCL	V _{CC} = MAX,	∨ ₁ = 4.5 ∨			1.2	2.2		1.2	2.2	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 \ddagger All typical values are at V_{CC} = 5 V, T_A = 25^oC.

§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
^t PLH	Алу	Y			9	15	ns
^t PHL					10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

			SN54S20			SN74S20			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			v	
VIL.	Low-level input voltage			0.8			0.8	v	
юн	High-level output current			- 1			- 1	mΑ	
IOL	Low-ievel output current			20			20	mΑ	
Τ _A	Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T	SN54S20	SN74S20	UNIT
		MIN TYP‡ MAX	ΜΙΝ ΤΥΡ‡ ΜΑΧ	
VIK	V _{CC} = MIN, I ₁ = -18 mA	-1.2	-1.2	v
VOH	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = - 1 mA	2.5 3.4	2.7 3.4	V
VOL	V _{CC} = MIN, V _{1H} = 2 V, I _{OL} = 20 mA	0,5	0.5	v
li i	V _{CC} = MAX, V ₁ = 5.5 V	1	1	mΑ
цн	V _{CC} = MAX, V ₁ = 2.7 V	50	50	μA
ЧĽ	V _{CC} = MAX, V ₁ = 0.5 V	-2	-2	mA
los§	V _{CC} = MAX	-40 -100	-40 -100	mA
ссн	V _{CC} = MAX, V _I = 0 V	5 8	58	mA
CCL	V _{CC} = MAX, V _I = 4.5 V	10 18	10 18	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions, ‡ All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$. § Not more then one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

2

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	МАХ	UNIT
tPLH			RL = 280 Ω, CL = 1	5	3	4.5	п\$
tPHL		Y -	ML - 200 32, OL - 1	56	3	5	nş
^t ₽ĽH	A, B, C or D		R _L = 280 Ω, C _L = 5	0.05	4.5		ns
^t PHL			n20032, 0[-3		5		ns

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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15-Oct-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/07006BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07006BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07006BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30007B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30007BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7420N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7420N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI

PACKAGE OPTION ADDENDUM

TEXAS INSTRUMENTS

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15-Oct-2009

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp
SN74LS20J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS20N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS20N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS20NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS20NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLI
SN74LS20NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74LS20NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74LS20NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74LS20NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNL
SN74S20DR	OBSOLETE	SOIC	D	0		TBD	Call TI	Call TI
SN74S20DR	OBSOLETE	SOIC	D	0		TBD	Call TI	Call TI
SN74S20N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S20N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5420W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI

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RUMENTS

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins F	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
SNJ5420W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5420WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ5420WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ54LS20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD:** The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*Al	dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS20DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS20NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS20DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS20NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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